

IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph [0022] beginning on page 8, at line 7, has been amended as follows:

Furthermore, the sensor board 134 is ~~a single layer~~ and attached to a lower surface of the lightguide 132 for receiving inputting signals from a hand-held stylus above the flat panel display. In a preferred embodiment, the sensor board has a thickness of 0.4~0.8 mm and comprises an antenna array layer and a reflector surface layer. The antenna array layer is made of FR4 or FPC materials and has a thickness of 0.2~0.4 mm for receiving electro-magnetic signals from the hand-held stylus. And the reflector surface layer has a thickness of 0.2~0.4 mm and can be formed on or beneath the antenna array layer basing process requirements to reflect the lights dispersed from the lower surface of said lightguide 132.

Paragraph [0024] beginning on page 9, at line 6, has been amended as follows:

It is noted that ~~a~~ an integrated control chip 122 is mounted onto the control circuit board 116 for executing the functions of driving the thin film transistors and decoding the signals from the sensor board. Namely the integrated control chip 122 is introduced to provide timing control signals for driving and controlling the thin film transistors, and simultaneously to provide logical functions of decoding and delivering signals from the sensor board 134.

Paragraph [0030] beginning on page 11, at line 9, has been amended as follows:

Compared to the conventional flat panel display, in the top view of the flat panel display provided by the present invention as shown in FIGURE 5, the sensor board 134 is fabricated in the casing of the backlight unit. Similarly, beneath the backlight unit a control circuit board 116 is fabricated and connected to the thin film transistors of the display module via the flexible printed circuit board 118. And because the control circuit board 116 is also applied to decode signal from the sensor board 134, one connecting bus 120 is introduced to connect the control

Application No. 10/624,478

circuit board 116 and the sensor board 134. Besides, as aforementioned, the integrated control chip 122 is mounted onto the control circuit board 116 to execute the functions of driving the thin film transistors and decoding the signals from the sensor board. And another connecting bus 123 is applied to connect the control circuit board 116 and the system motherboard.